

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Nishant Sinha

Serial No.: 10/668,914

Filed: September 23, 2003

**For: PROCESS AND INTEGRATION
SCHEME FOR FABRICATING
CONDUCTIVE COMPONENTS,
THROUGH-VIAS AND
SEMICONDUCTOR COMPONENTS
INCLUDING CONDUCTIVE THROUGH-
WAFER VIAS**

**VIA ELECTRONIC FILING
June 25, 2007**

Confirmation No.: 2525

Examiner: W. Lindsay Jr.

Group Art Unit: 2812

**Attorney Docket No.: 2269-5859US
(02-0390.00/US)**

**FEE ADDRESSEE FOR RECEIPT OF PTO NOTICES
RELATING TO MAINTENANCE FEES**

**Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450**

Sir:

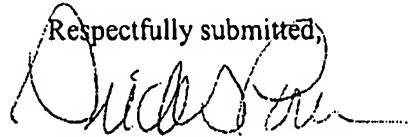
1. This letter is to specify that the FEE ADDRESSEE for this patent is:

**MICRON TECHNOLOGY, INC.
Mail Stop 525
8000 South Federal Way
Boise, Idaho 83707-0006**

Serial No. 10/668,914

2. The Customer Number for the Fee Addressee is 26809.
3. Any prior FEE ADDRESSEE for this patent is hereby revoked.
4. It is certified that the person whose signature appears below has the authority to change the FEE ADDRESSEE for this patent.

Respectfully submitted,



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Date: June 25, 2007

BGP/dlm:eg
Document in ProLaw